

Title (en)

Method of manufacturing a pattern of an electrically conductive polymer on a substrate surface and method of metallizing such a pattern

Title (de)

Herstellungsverfahren eines Musters von einem elektrisch leitfähigen Polymer auf einer Substratoberfläche und Metallisierung eines solchen Musters

Title (fr)

Méthode de fabrication d'une configuration d'un polymère électroconducteur à la surface d'un substrat et procédé de métallisation de cette configuration

Publication

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Application

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Priority

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Abstract (en)

[origin: EP0615256A2] A solution of monomers, oligomers or polymers and a suitable oxidation agent can be stable if the solution also comprises a base. By spin coating this solution onto a substrate, a layer can be formed which, after patterned irradiation, yields a pattern of a doped conductive polymer which is formed in situ, the exposed and unexposed areas exhibiting a large difference in conductivity. A description is given of, inter alia, the patterned irradiation of a layer of 3,4-ethylenedioxythiophene. If desired, the conductive polymer pattern can subsequently be metallized in an electroplating bath. The method provides, inter alia, a simple process of manufacturing metal patterns on insulating substrates, such as printed circuit boards. <IMAGE>

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